

## IN THE ABSTRACT

Please replace the abstract with the following amended abstract:

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A method of making a stackable microcircuit layer formed from a plastic encapsulated microcircuit (PEM) is disclosed. The method involves the steps of starting with a commercially available PEM (e.g. a plastic Thin Small Outline Package or TSOP) that contains a microcircuit or die within an encapsulant and modifying the PEM to expose conductive members that are electrically connected to the microcircuit's bond pads. In the case of a TSOP, the preferred modifying step is accomplished by top grinding the TSOP in order to remove the lead frame that was secured above the die and encapsulated along with it in the TSOP. Reroute metallization is then applied in order to connect the conductive members that were exposed by the top grinding, to an edge of the modified PEM.

## IN THE CLAIMS

Please substitute the following claims for the pending claims of the same number:

~~1. (Amended) A method of making a stackable microcircuit layer comprising the steps of:~~

providing a plastic encapsulated microcircuit (PEM), the PEM including

A3  
✓ (a) a microcircuit having an active surface containing integrated circuitry and a bond pad, and

(b) an encapsulant in contact with and encasing the microcircuit; and